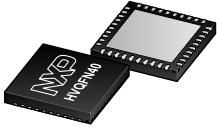


SOT618-21(D)

HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

10 October 2024

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-11-2024
Manufacturer package code	98ASA01939D

Table 1. Package summary

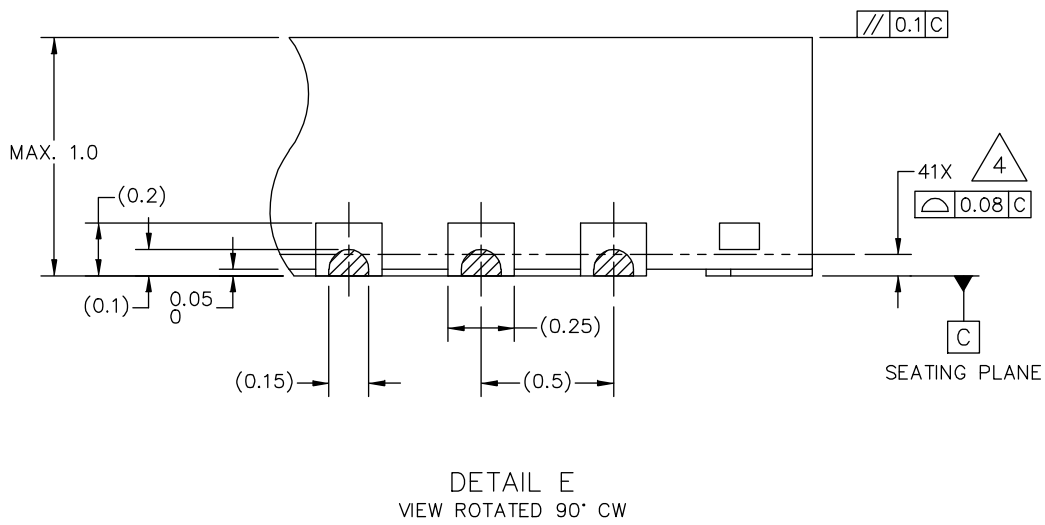
Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	-	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-21(D)



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Figure 2. Package outline detail E of HVQFN40 (SOT618-21(D))

HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

3 Soldering

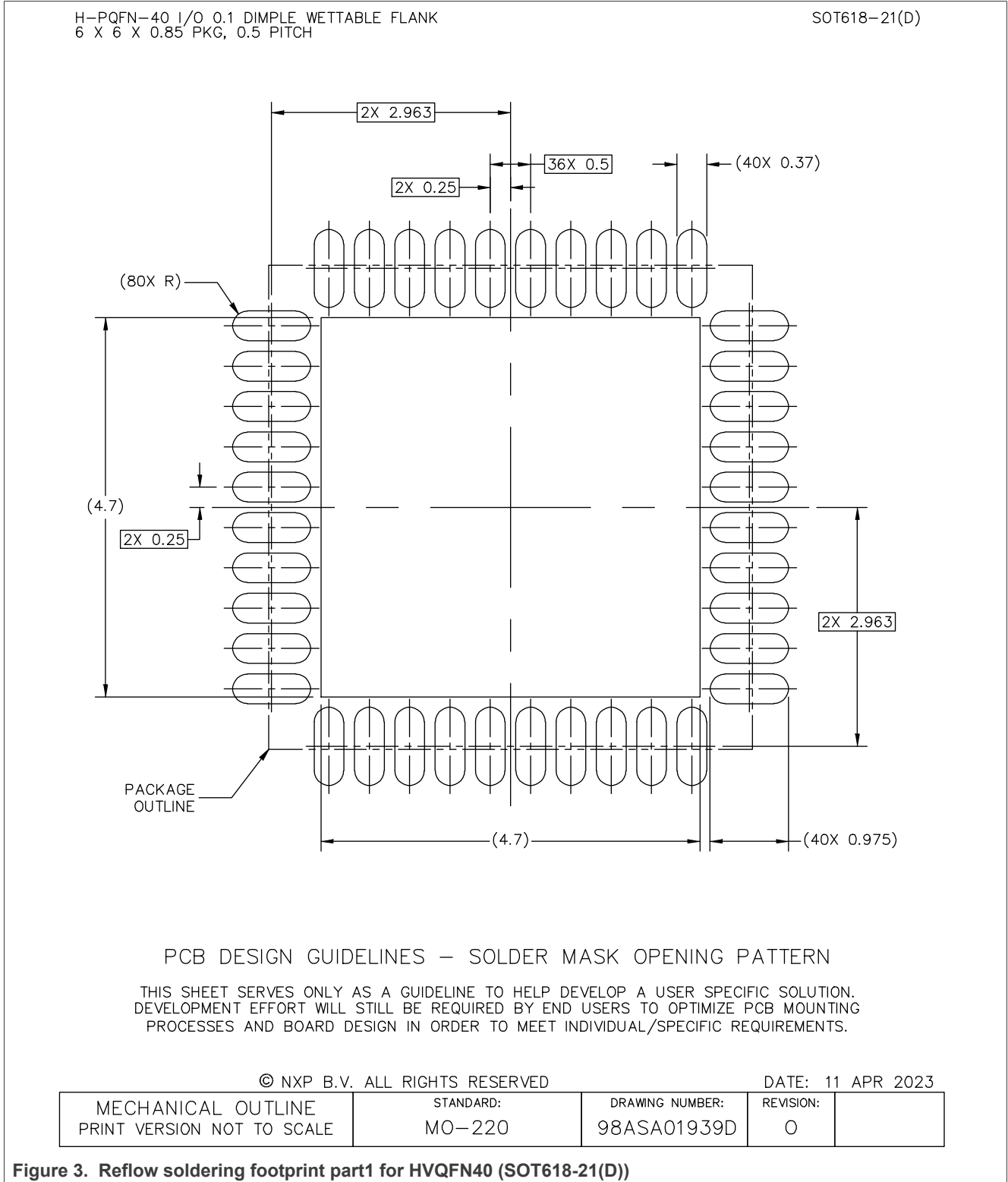
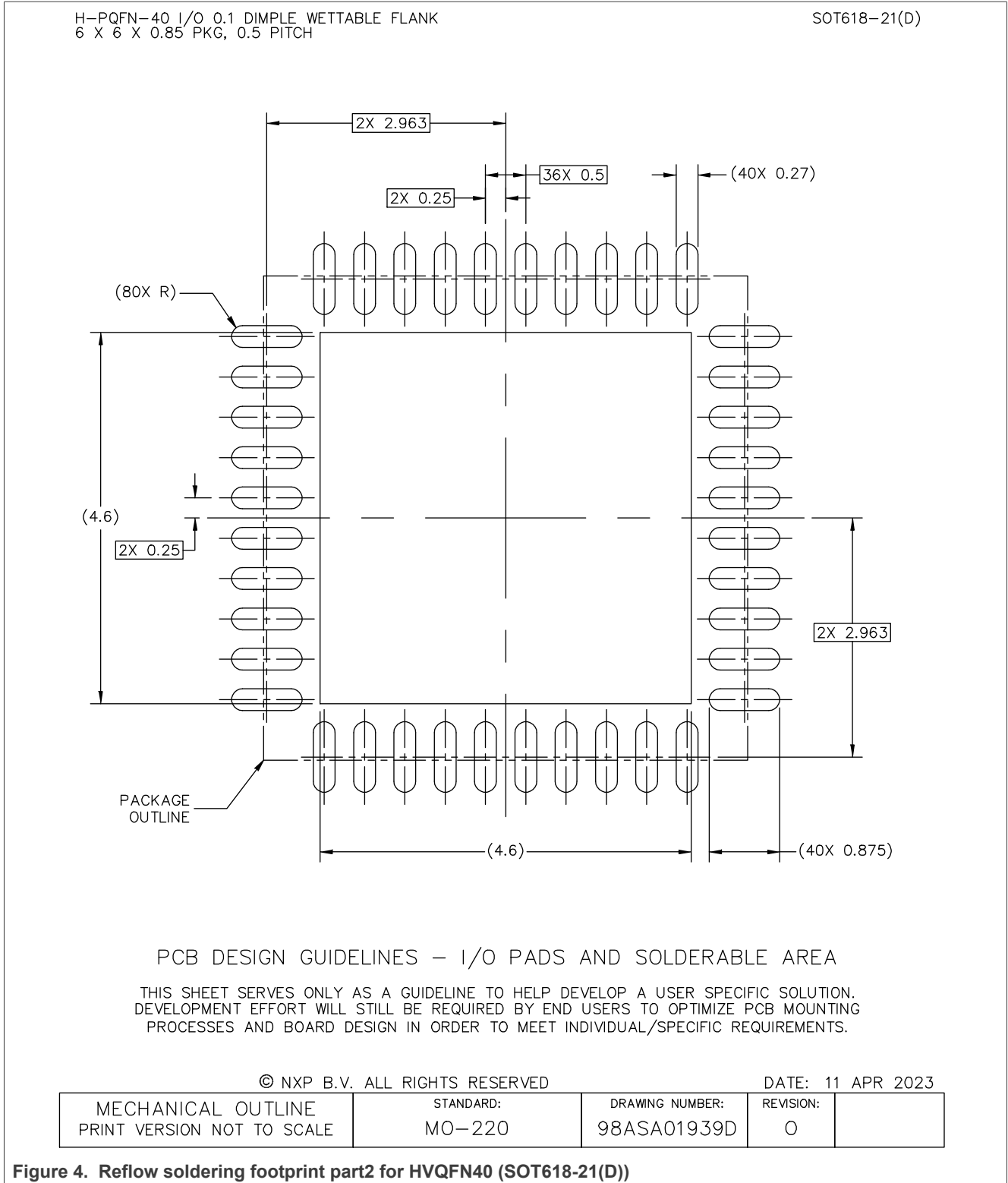
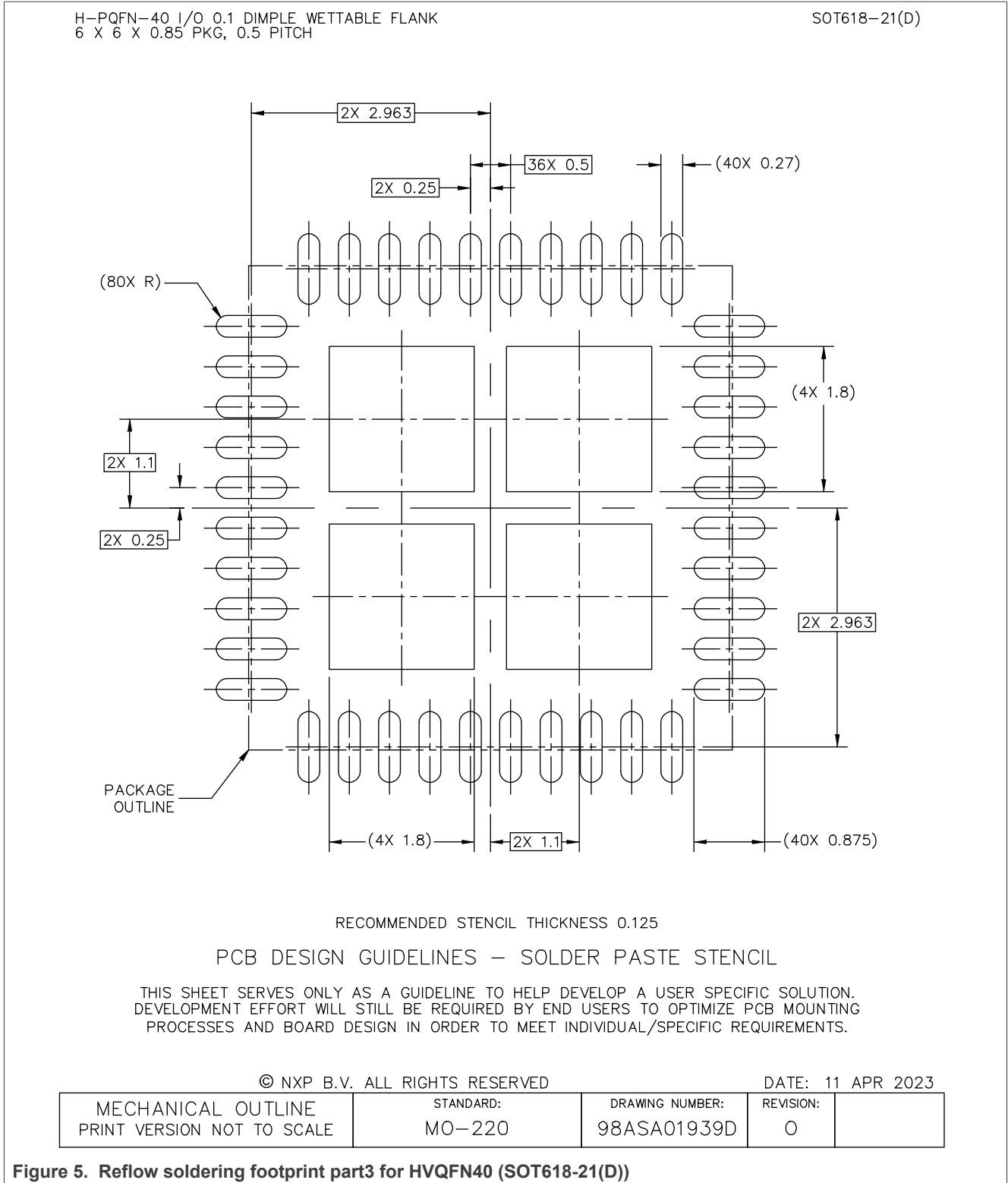


Figure 3. Reflow soldering footprint part1 for HVQFN40 (SOT618-21(D))

HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body



HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body



HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-21(D)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, ANCHORING PADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN40 (SOT618-21(D))

HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

4 Legal information

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HVQFN40, plastic thermal enhanced very thin quad flat wettable flanks package; no leads; 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

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